Amendments to the Specification:

Please replace the paragraph beginning at page 3, line 5, with the following:

~~FIG. 2 is a drawing in part of a circuit protector in accordance with an exemplary embodiment of the present invention.~~FIG. 2A is a explanatory view showing a heat diffusion in a circuit protector in accordance of the present invention.

FIG. 2B is a explanatory view showing a heat diffusion in a prior art circuit protector.

Please replace the paragraph beginning at page 3, line 7, with the following:

FIG. 3 is a perspective view of a circuit protector shown in FIG. 1~~in accordance with an exemplary embodiment of the present invention~~.

Please replace the paragraph beginning at page 5, line 3, with the following:

FIG. 1 is a perspective view of a circuit protector in accordance with an exemplary embodiment of the present invention. ~~FIG. 2~~FIG. 2A shows the circuit protector of FIG. 1 as viewed from the direction Z, with part of the protection material 14 removed.

Please replace the paragraph beginning at page 16, line 13, with the following:

The grooves 13b, 13c reduces diffusion of the heat generated at the narrowed portion 13a towards the terminals 15, 16 via the conductive layer. When such a circuit protector is mounted on a board, diffusion of the heat to the board via terminals 15, 16 can be reduced, as a result the pre-arcing time can be shortened. A heat diffusion in the conductive layer 12 is shown in FIG. 2A. ~~Without the grooves 13b, 13c, the heat diffusion is as shown in FIG. 2B.~~ Without the grooves 13b and 13c, that is in a case of a conductive layer of the prior art, the heat diffusion occurs as shown in FIG. 2B, where a heat generated at the narrowed

portion is easily diffused to the terminals, and then to the board. As a heat accumulation to melt down the conductive layer at the narrowed portion becomes small, the pre-arcing time becomes long. The arrow in FIG. 2A, 2B indicate the route of heat diffusion.